Product Preview

32K x 8 Bit Static Random Access Memory

The MCM6706B is a 262,144 bit static random access memory organized as 32,768 words of 8 bits. Static design eliminates the need for external clocks or timing strobes.

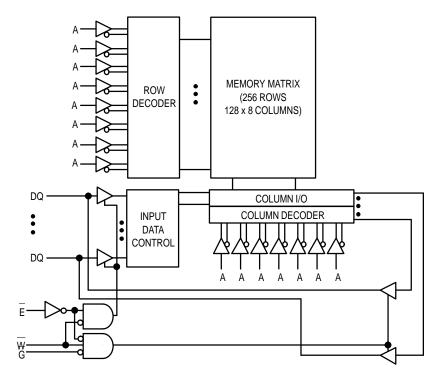
Output enable (G) is a special control feature that provides increased system flexibility and eliminates bus contention problems.

The MCM6706B is available in a 300 mil, 28-lead surface-mount SOJ package.

- Single 5.0 V \pm 10% Power Supply
- Fully Static No Clock or Timing Strobes Necessary
- All Inputs and Outputs Are TTL Compatible
- Three State Outputs
- Fast Access Times: MCM6706B-8 = 8 ns MCM6706B-10 = 10 ns

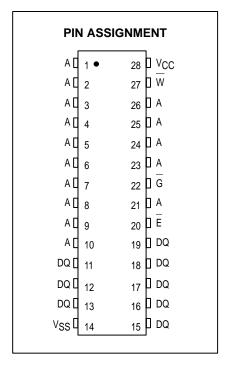
MCM6706B-12 = 12 ns

BLOCK DIAGRAM



MCM6706B





A. Address Input W Write Enable E. Chip Enable G Output Enable DQ Data Input/Output VCC + 5.0 V Power Supply VSS Ground

This document contains information on a new product under development. Motorola reserves the right to change or discontinue this product without notice.

REV 1 10/9/96



TRUTH TABLE (X = Don't Care)

E	G	w	Mode	I/O Pin	Cycle
Н	Х	Х	Not Selected	High–Z	_
L	Н	Н	Read	High–Z	_
L	L	Н	Read	D _{out}	Read Cycle
L	Х	L	Write	D _{in}	Write Cycle

ABSOLUTE MAXIMUM RATINGS (See Note)

Rating	Symbol	Value	Unit
Power Supply Voltage	VCC	- 0.5 to + 7.0	V
Voltage Relative to V _{SS} for Any Pin Except V _{CC}	V _{in} , V _{out}	- 0.5 to V _{CC} + 0.5	V
Output Current	l _{out}	± 30	mA
Power Dissipation	PD	2.0	W
Temperature Under Bias	T _{bias}	- 10 to + 85	°C
Operating Temperature	T _A	0 to + 70	°C
Storage Temperature — Plastic	T _{stg}	- 55 to + 125	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPER-ATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high–impedance circuit.

This BiCMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow of at least 500 linear feet per minute is maintained.

DC OPERATING CONDITIONS AND CHARACTERISTICS

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, T_A = 0 \text{ to } 70^{\circ}\text{C}, \text{ Unless Otherwise Noted})$

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Тур	Max	Unit
Supply Voltage (Operating Voltage Range)	Vcc	4.5	5.0	5.5	V
Input High Voltage	VIH	2.2	_	V _{CC} + 0.3*	V
Input Low Voltage	V _{IL}	- 0.5**	_	0.8	V

 $^{^*}$ V_{IH} (max) = V_{CC} + 0.3 V dc; V_{IH} (max) = V_{CC} + 2.0 V ac (pulse width \leq 2.0 ns) or I \leq 30.0 mA.

DC CHARACTERISTICS

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, V _{in} = 0 to V _{CC})	llkg(l)	_	± 1.0	μΑ
Output Leakage Current (E = V _{IH} or G = V _{IH} , V _{out} = 0 to V _{CC})	l _{lkg(O)}	_	± 1.0	μΑ
Output High Voltage (I _{OH} = - 4.0 mA)	Voн	2.4	_	V
Output Low Voltage (I _{OL} = + 8.0 mA)	VoL	_	0.4	V

POWER SUPPLY CURRENTS

Parameter	Symbol	6706B-8	6706B-10	6706B-12	Unit	Notes
AC Active Supply Current (I _{out} = 0 mA, V _{CC} = max, f = f _{max})	ICCA	195	185	175	mA	1, 2, 3
AC Standby Current (E = V_{IH} , V_{CC} = max, f = f_{max})	I _{SB1}	75	70	65	mA	1, 2, 3
CMOS Standby Current (V_{CC} = max, f = 0 MHz, E \geq V_{CC} - 0.2 V, $V_{in} \leq$ V_{SS} , or \geq V_{CC} - 0.2 V)	I _{SB2}	20	20	20	mA	

NOTES:

- 1. Reference AC Operating Conditions and Characteristics for input and timing $(V_{IH}/V_{IL},\,t_f/t_f,\,pulse\,level\,0$ to 3 V, $V_{IH}=3$ V).
- 2. All addresses transition simultaneously low (LSB) and then high (MSB).
- 3. Data states are all zero.

^{**} V_{IL} (min) = -0.5 V dc @ 30.0 mA; V_{IL} (min) = -2.0 V ac (pulse width ≤ 2.0 ns) or $I \le 30.0$ mA.

CAPACITANCE (f = 1.0 MHz, dV = 3.0 V, T_A = 25°C, Periodically Sampled Rather Than 100% Tested)

Parameter	Symbol	Max	Unit
Address Input Capacitance	C _{in}	5	pF
Control Pin Input Capacitance (E, G, W)	C _{in}	6	pF
I/O Capacitance	C _{out}	6	pF

AC OPERATING CONDITIONS AND CHARACTERISTICS

(V_{CC} = 5.0 V \pm 10%, T_A = 0 to + 70°C, Unless Otherwise Noted)

Input Timing Measurement Reference Level 1.5 V	Output Timing Measurement Reference Level 1.5 V
Input Pulse Levels 0 to 3.0 V	Output Load See Figure 1a
Input Rise/Fall Time	

READ CYCLE (See Notes 1 and 2)

		MCM6706B-8		MCM6706B-10		B-10 MCM6706B-12			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Read Cycle Time	tavav	8	_	10	_	12	_	ns	3
Address Access Time	tAVQV	_	8	_	10	_	12	ns	
Chip Enable Access Time	^t ELQV	_	8	_	10	_	12	ns	
Output Enable Access Time	^t GLQV	_	4	_	5	_	6	ns	
Output Hold from Address Change	^t AXQX	3	_	3	_	3	_	ns	
Chip Enable Low to Output Active	^t ELQX	1	_	1	_	1	_	ns	4 ,5, 6
Chip Enable High to Output High–Z	^t EHQZ	_	4.5	_	5	_	6	ns	4, 5, 6
Output Enable Low to Output Active	^t GLQX	0	_	0	_	0		ns	4, 5, 6
Output Enable High to Output High–Z	^t GHQZ	_	4	_	5	_	6	ns	4, 5, 6

NOTES:

- 1. W is high for read cycle.
- 2. Product sensitivites to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
- 3. All read cycle timing is referenced from the last valid address to the first transitioning address.
- 4. At any given voltage and temperature, tehoz max < telox min, and tohoz max < telox min, both for a given device and from device to device.
- 5. Transition is measured 200 mV from steady-state voltage with load of Figure 1b.
- 6. This parameter is sampled and not 100% tested.
- 7. Device is continuously selected $(E = V_{IL}, G = V_{IL})$.
- 8. Addresses valid prior to or coincident with E going low.

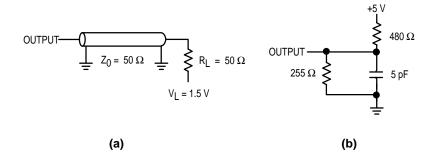


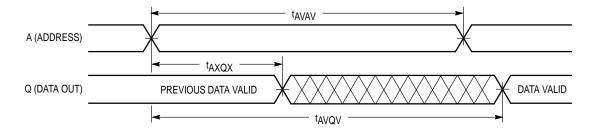
Figure 1. AC Test Loads

TIMING LIMITS

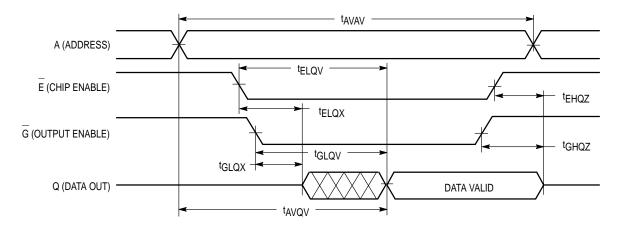
The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the system must supply at least that much time. On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device never provides data later than that time.

MOTOROLA FAST SRAM MCM6706B

READ CYCLE 1 (See Note 7)



READ CYCLE 2 (See Note 8)



MCM6706B MOTOROLA FAST SRAM

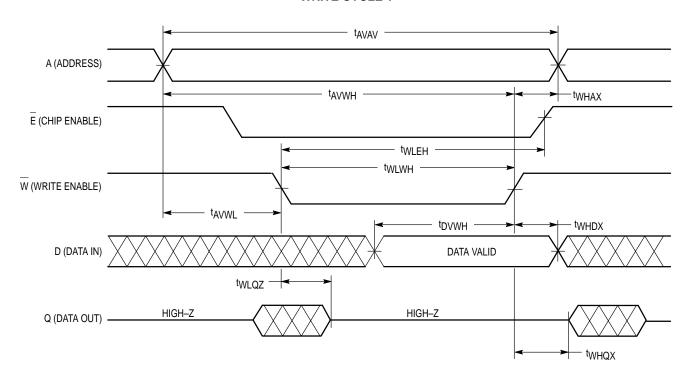
WRITE CYCLE 1 (W Controlled, See Notes 1 and 2)

		MCM6706B-8		MCM6706B-10		-10 MCM6706B-12			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Time	t _{AVAV}	8	_	10	_	12	_	ns	3
Address Setup Time	tAVWL	0	_	0	_	0	_	ns	
Address Valid to End of Write	^t AVWH	8	_	9	_	10	_	ns	
Write Pulse Width	tWLWH, tWLEH	8	_	9	_	10	_	ns	
Data Valid to End of Write	tDVWH	4	_	5	_	6	_	ns	
Data Hold Time	tWHDX	0	_	0	_	0	_	ns	
Write Low to Data High–Z	tWLQZ	_	4	_	5	_	6	ns	4, 5, 6
Wirte High to Output Active	tWHQX	3	_	3	_	3	_	ns	4, 5, 6
Write Recovery Time	tWHAX	0	_	0	_	0	_	ns	

NOTES:

- 1. A write occurs during the overlap of E low and W low.
- 2. Product sensitivites to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
- 3. All write cycle timings are referenced from the last valid address to the first transitioning address.
- 4. Transition is measured 200 mV from steady-state voltage with load of Figure 1b.
- 5. Parameter is sampled and not 100% tested.
- 6. At any given voltage and temperature, t_{WLQZ} max is $< t_{WHQX}$ min both for a given device and from device to device.

WRITE CYCLE 1



MOTOROLA FAST SRAM MCM6706B

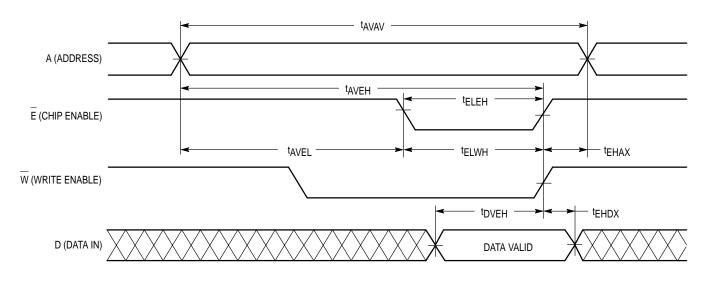
WRITE CYCLE 2 (E Controlled, See Notes 1 and 2)

		MCM6706B-8		6B-8 MCM6706B-10		MCM6706B-12			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Time	^t AVAV	8	_	10	_	12	_	ns	3
Address Setup Time	^t AVEL	0	_	0	_	0	_	ns	
Address Valid to End of Write	^t AVEH	8	_	9	_	10	_	ns	
Chip Enable to End of Write	tELWH, tELEH	7	_	8	_	9	_	ns	4,5
Data Valid to End of Write	^t DVEH	4	_	5	_	6	_	ns	
Data Hold Time	tEHDX	0	_	0	_	0	_	ns	
Write Recovery Time	t _{EHAX}	0	_	0		0		ns	

NOTES:

- 1. A write occurs during the overlap of E low and W low.
- 2. Product sensitivites to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
- 3. All write cycle timing is referenced from the last valid address to the first transitioning address.
- 4. If E goes low coincident with or after W goes low, the output will remain in a high impedance condition.
 5. If E goes high coincident with or before W goes high, the output will remain in a high impedance condition.

WRITE CYCLE 2

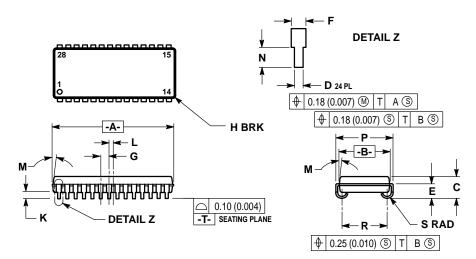


HIGH-Z Q (DATA OUT) -

MOTOROLA FAST SRAM MCM6706B

PACKAGE DIMENSIONS

J PACKAGE 300 MIL SOJ CASE 810B-03

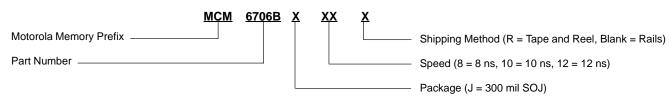


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- DIMENSION A & B DO NOT INCLUDE MOLD PROTRUSION. MOLD PROTRUSION SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 3 CONTROLLING DIMENSION: INCH
- 4. DIM R TO BE DETERMINED AT DATUM -T-.

	MILLIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	18.29	18.54	0.720	0.730
В	7.50	7.74	0.295	0.305
С	3.26	3.75	0.128	0.148
D	0.39	0.50	0.015	0.020
Е	2.24	2.48	0.088	0.098
F	0.67	0.81	0.026	0.032
G	1.27	BSC	0.050	BSC
Н	_	0.50		0.020
K	0.89	1.14	0.035	0.045
L	0.64	BSC	0.025	BSC
M	0°	10°	0°	10°
N	0.76	1.14	0.030	0.045
Р	8.38	8.64	0.330	0.340
R	6.60	6.86	0.260	0.270
S	0.77	1.01	0.030	0.040

ORDERING INFORMATION (Order by Full Part Number)



Full Part Numbers — MCM6706BJ8 MCM6706BJ8R MCM6706BJ10 MCM6706BJ10R MCM6706BJ12R

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